



PRODUCT SPECIFICATION

SLM-3535RGB-002

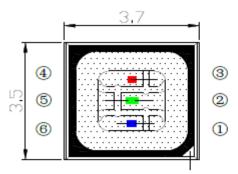
Unit 24, 6/F, Goldfield Industrial Centre, 1 Sui Wo Road, Fo Tan, Shatin, Hong Kong. Tel: 852 - 2687 4379 Fax: 852 - 2687 3374 <u>http://www.seam-asia.com</u>

1 of 9

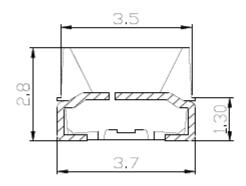
| File No: LM-DS-00011-161125 | Rev: 3.0 | Page |
|-----------------------------|----------|------|
|-----------------------------|----------|------|

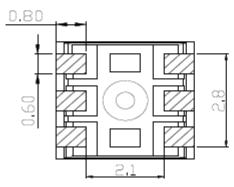


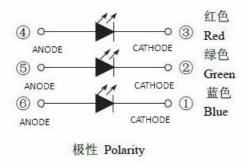
Outline Dimension

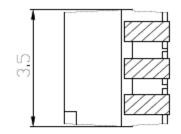


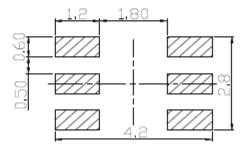
Cathode marking











推荐焊盘 Recommended Soldering Pad

Note: All dimensions in mm. Tolerances: X.X ±0.1 mm X.XX ±0.05mm



Absolute maximum ratings at Ta=25°C

| Parameter | | Symbol | Rating | Unit |
|-------------------------|---|--------|-----------|------|
| | R | | 60 | |
| Power Dissipation | G | PD | 90 | mW |
| | В | | 90 | |
| Forward Current | | IF | 25 | mA |
| Peak Forward Current *1 | | IFP | 100 | mA |
| Reverse Voltage | | VR | 5 | V |
| Electrostatic Discharge | | ESD | 2000 | V |
| Operating Temperature | | Topr | -30~+85 | °C |
| Storage Temperature | | Tstg | -40 ~+100 | °C |

* Pulse width≤0.1msec Duty Ratio ≤1/10

Electro-optical characteristics at Ta=25°C

| Parameter | | Symbol | Min | Тур | Max | Unit | Condition |
|------------------------------|---|--------------------------|------|------|------|------|-----------|
| | R | | 1.8 | - | 2.6 | | |
| Forward Voltage | G | Vf | 2.8 | 3.2 | 3.6 | V | |
| | В | | 2.8 | 3.2 | 3.6 | | |
| | R | | 500 | 850 | 1450 | | |
| Luminous Intensity | G | lv | 1100 | 2350 | 3000 | mcd | |
| | В | | 260 | 540 | 850 | | IF=20mA |
| Dominant Wavelength | R | λD | 615 | 620 | 630 | nm | |
| | G | | 515 | 520 | 535 | | |
| | В | | 465 | 470 | 480 | | |
| | R | | - | 20 | - | | |
| Spectrum Radiation Bandwidth | G | Δλ | - | 35 | - | nm | |
| | В | | - | 30 | - | | |
| View Angle | | 20 _{1/2} | - | 110 | - | deg | - |
| Reverse Current | | IR | - | - | 10 | μA | VR=5V |



Bin Grouping:

Luminous Intensity

| | Blue (mcd) | | Green (mcd) | | | Red (mcd) | | |
|------|------------|------|-------------|------|------|-----------|------|------|
| Rank | Min. | Max. | Rank | Min. | Max. | Rank | Min. | Max. |
| B1 | 260 | 380 | G1 | 1100 | 1800 | R1 | 500 | 650 |
| B2 | 380 | 495 | G2 | 1800 | 2350 | R2 | 650 | 850 |
| B3 | 495 | 650 | G3 | 2350 | 3000 | R3 | 850 | 1100 |
| B4 | 650 | 850 | | | | R4 | 1100 | 1450 |

Wavelength

| | Blue | (nm) | Green (nm) | | Red (nm) | |
|------|------|------|------------|------|----------|-----|
| Rank | Min. | Max. | Min. | Max. | Min. | Max |
| Full | 465 | 480 | 515 | 535 | 615 | 630 |
| W | 465 | 470 | 515 | 520 | 615 | 620 |
| х | 470 | 475 | 520 | 525 | 620 | 625 |
| Y | 475 | 480 | 525 | 530 | 625 | 630 |
| Z | | | 530 | 535 | | |

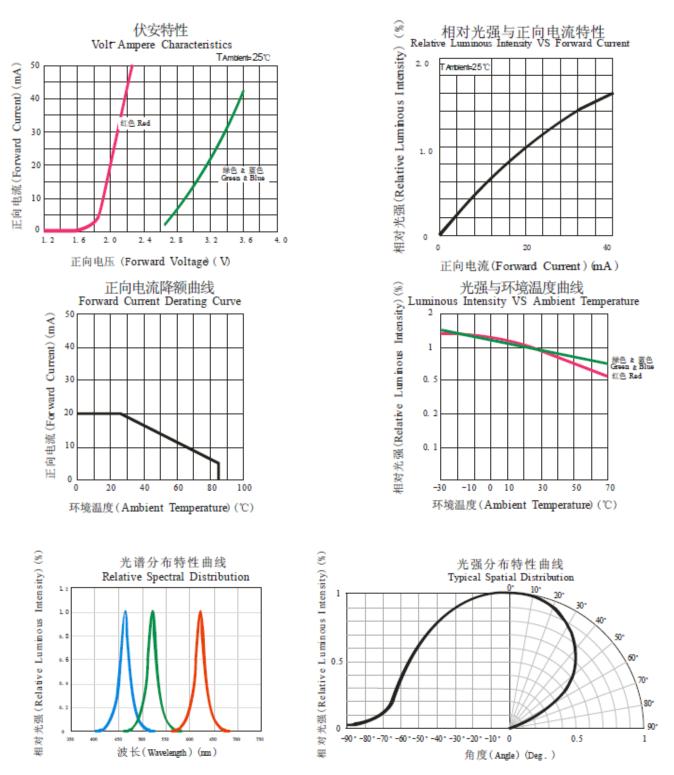
Forward Voltage

| | Blue (V) | | Green (V) | | Red (V) | |
|------|----------|------|-----------|------|---------|-----|
| Rank | Min. | Max. | Min. | Max. | Min. | Max |
| V1 | 2.8 | 3.6 | 2.8 | 3.6 | 1.8 | 2.6 |

| File No: LM-DS-00011-161125 | Rev: 3.0 | Page 4 of 9 |
|-----------------------------|----------|-------------|
|-----------------------------|----------|-------------|



Typical Characteristics Curves



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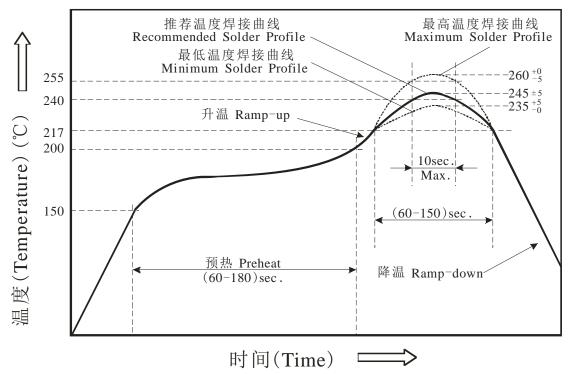


Guideline for Soldering

1. Hand Soldering

A soldering iron of less than 20W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300° C while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

- Be careful because the damage of the product is often started at the time of the hand soldering.
- 2. Reflow Soldering: Use the conditions shown in the under figure of Pb-Free Reflow Soldering.



Reflow soldering should not be done more than two times.

Stress on the LEDs should be avoided during heating in soldering process.

After soldering, do not deal with the product before its temperature drop down to room temperature.

3. Cleaning

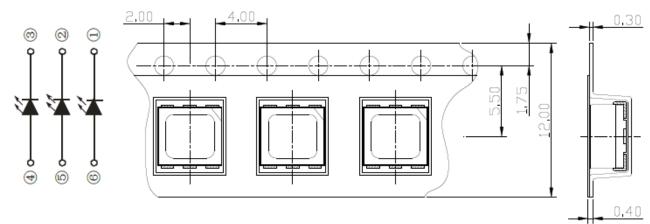
It is recommended that alcohol be used as a solvent for cleaning after soldering Cleaning is to go under 30° C for 3 minutes or 50° C for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin of not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pre-test should be done to confirm whether ang damage to LEDs will occur.

*Note: This general guideline may not apply to all PCE designs and configurations of all soldering equipment. The technics in practice is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment.

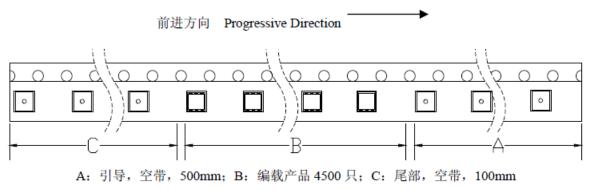


Packaging Carrier Tape



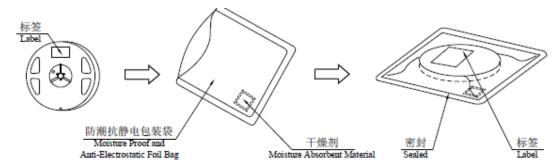
All dimensions in mm, tolerances unless mentioned is ± 0.1 mm.

Details of Carrier Tape



A: Leader, Empty, 500mm; B:4500 Lamps Loaded; C: Trailer, Empty, 100mm.

Moisture Proof and Anti-Electrostatic Foil Bag



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Precautions

1. Storage

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum. Before opening the package, the product should be kept at 30° C or less and humidity less than 60% RH, and be used within a year. After opening the package, the product should be stored at 30° C or less and humidity less than 10° RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30° C or less and humidity less than 60° RH.

If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (60±5)°C for 24 hours.

2. Static Electricity

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current., even not light. All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs



Revision History

| Page | Subjects | Date of Modification | | |
|--------|--|----------------------|--|--|
| | New Format | 31-Jul-2013 | | |
| 3 4 | Adjust Green Chip Luminous Intensity Add Bin Grouping | 05-Dec-2013 | | |
| 3 | Added ESD Information | 31-Jul-2014 | | |
| 7 | Correction - Packing drawing 2,500pcs to 3,000pcs Reel | 05-Nov-2014 | | |
| 7 | Updated – Packing drawing From 3,000pcs adjust to 4,500pcs per Reel | 25-Nov-2016 | | |
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| File No: LM-DS-00011-161125 | Rev: 3.0 | Page 9 of 9 |
|-----------------------------|----------|-------------|
|-----------------------------|----------|-------------|